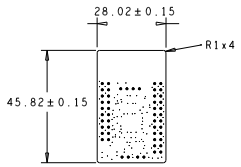
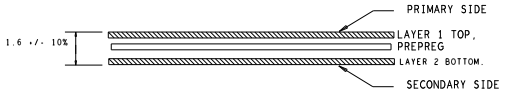
| REVISIONS | | | |
|---|---|---|---|
| REV | DESCRIPTION | DATE | APPROVED |
| 1.0B | INITIAL RELEASE | WW1525 | LIKZ |
| 1.1 | CHANGE CYBLE No.;CHANGE TO 10PIN MP;CHANGE PIN MAP | WW1533 | LIKZ |




| DRILL CHART: TOP to BOTTOM | | | | |
|---|---|---|---|---|
| ALL UNITS ARE IN MILS | | | | |
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| · | 10.0 | +3.0/-3.0 | PLATED | 115 |
| • | 39.0 | +3.0/-3.0 | PLATED | 52 |




NOTES (UNLESS OTHERWISE SPECIFIED):

1. GENERAL
   - 1.0 PCB MUST BE ROHS COMPLIANT. ~~#F COMPLIANT.~~
   - 1.1 STANDARDS-ALL RAW CARDS MUST CONFORM TO IPC6011/IPC-6012 CLASS 2 USING THE MOST CURRENT REVISION LEVEL.
   - 1.2 FOR INSPECTION, BOARDS MUST MEET THE REQUIREMENTS OF THE LEVEL OF IPC-600 USING THE MOST CURRENT REVISION LEVEL.
2. MATERIAL
   - 2.0 NEMA GRADE FR-4 140 MIN.
   - 2.1 SEE LAYER STACKUP DETAIL FOR FINISHED COPPER LAYERS AND PCB THICKNESS.
   - 2.2 FLAMMABILITY RATING 94V-0.
3. ETCH
   - 3.0 ETCH TOLERANCE ON ALL FOIL FEATURES INCLUDING FINISHED TRACE WIDTH AND SPACING TOLERANCE IS +/-15% OF THE ORIGINAL ARTWORK/GERBER DESIGN.
   - 3.1 THE ARTWORK/GERBER DESIGN MINIMUM TRACE WIDTH IS 0.004 INCH AND THE MINIMUM COPPER TO COPPER SPACING IS 0.004 INCH.
4. LAYER STRUCTURE
   - 4.0 REFER TO DETAIL STACKUP FIGURE FOR LAYER STRUCTURE AND ASSOCIATED ARTWORK.
5. FINISH
   - 5.0 PLATE THRU WITH COPPER.
   - 5.1 FINISH SURFACE: ENIG
   - 5.2 COPPER PLATING IN THRU-HOLES:0.001 INCH MIN.
6. SOLDERMASK
   - 6.1 SOLDERMASK TO BE GREEN.
   - 6.2 SOLDERMASK TO BE IN ACCORDANCE WITH IPC-SM-840C CLASS T.
7. DRILLING
   - 7.0 DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-0.003 INCH TOL. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   - 7.1 TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
8. MARKING
   - 8.0 MARKING TO BE WHITE.
   - 8.1 MARKING NOT TO ENCROACH ON SURFACE MOUNT LANDS.
   - 8.2 FABRICATOR SHOULD ADD DATE CODE AND LOGO ON WHERE CYPRESS INDICATES.
9. VENDOR OPTIONS/REQUIREMENTS
   - 9.0 VENDORS MAY MAKE THE FOLLOWING CHANGES WITHOUT CYPRESS APPROVAL:
     - ADD TEARDROPS
   - 9.1 ANY OTHER CHANGES NEED WRITTEN APPROVAL FROM CYPRESS.
10. WARP/TWIST
    - 10.0 MAXIMUM WARP OR TWIST SHALL NOT EXCEED 0.5%.

| UNLESS OTHERWISE SPECIFIED | SIGNATURES | DATE |
|---|---|---|
| DIMENSIONS ARE IN INCHES | | |
| TOLERANCES ON; ANGLES +/- 2° | DRAWN LIKZ | WW1534 |
| 2 PL DECIMALS +/- .010 | CHECKED LIKZ | WW1534 |
| 3 PL DECIMALS +/- .005 | ENGRG | |
| THIRD ANGLE PROJECTIONS | ISSUED | |

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SAN JOSE, CA 95134
(408) 943-2600

| SIZE | FSCM NO | DWG NO | REV |
|---|---|---|---|
| C | | 610-20083-01 | 1.1 |

SCALE: 1/1 SHEET: